

“Microwave and Millimeter Wave Multi-Chip Module Manufacturing”

HXI, LLC / Monzite Corporation

Presented at iMAPS New England
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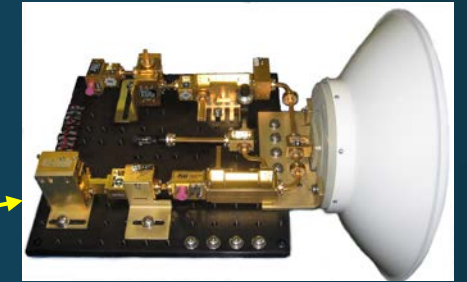
HXI Company Info

- **Company formed as Harmonix in 1992 and grew with financial assistance from SoftBank and Omron**
- **Main facility located in Harvard, MA (Shared with parent company – Renaissance Electronics & Communications)**
- **Employee backgrounds include Alpha Industries (Skyworks), Arcom Wireless, Millitech, Endwave & others**
- **Services military, commercial and space customers**
- **ITAR controlled facility and able to facilitate classified programs**
- **AS9100C & ISO9001:2008**



HXI Products

- Millimeter Wave Components
- Radar Front Ends, X-Band to W-Band
Ka-Band Transceivers for UAV Tracking & Landing
- Point-to-Point MMW Radios (GigaLink)
- Test Instrumentation (Farran products)
- Custom Test Components and Subsystems for Auto
Radar, WiGig, 5G and other MMW Applications



Monzite Company

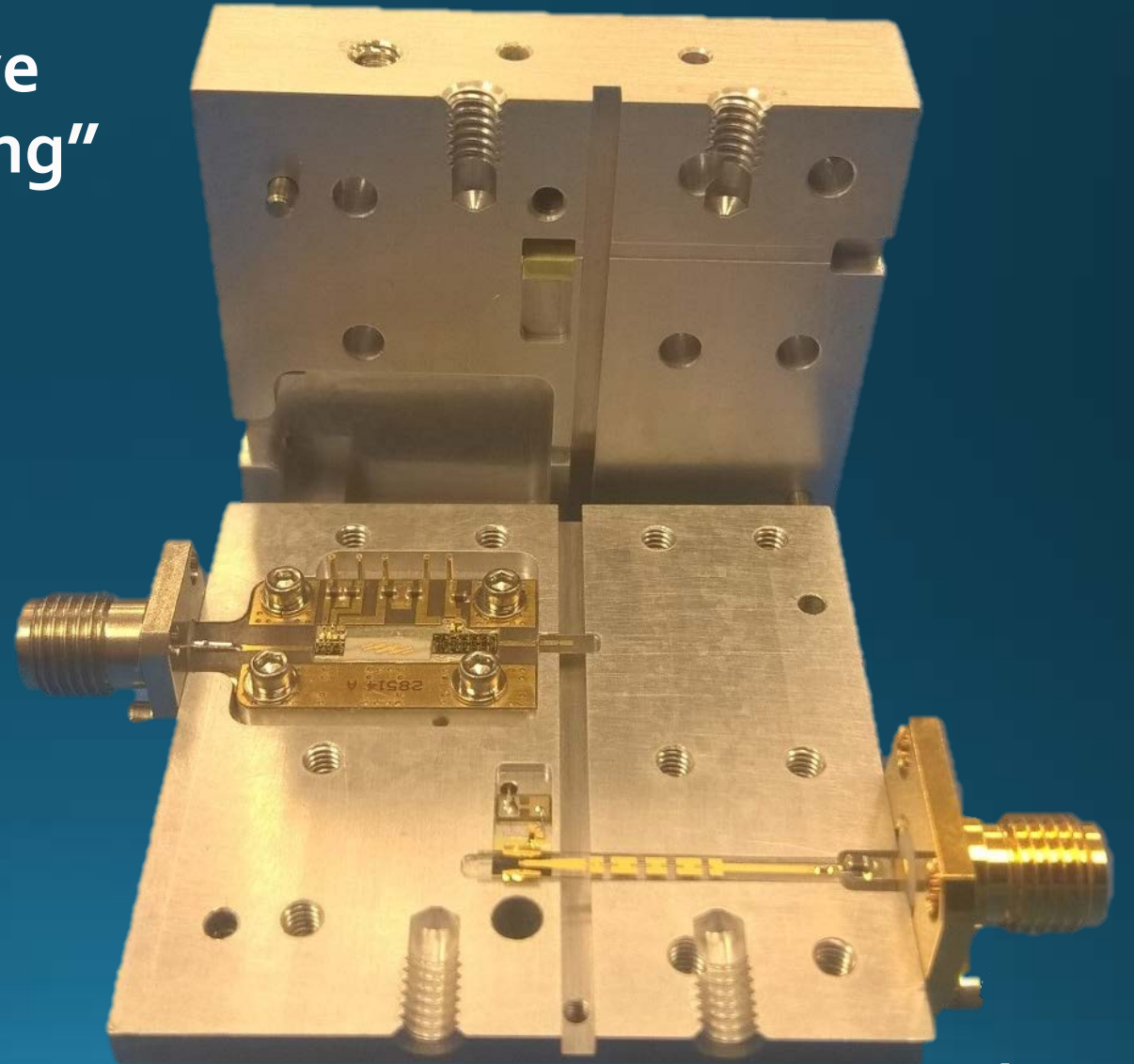
- Company formed as Monzite in 2013 merged with Impellimax
- Manufacturing facility located in Nashua, NH Monzite EMS Electronic Manufacturing Services and Impellimax brand electronic components
- Employee backgrounds include Alpha Industries (Skyworks), Micronetics Inc., Arcom Wireless, AD Micro-Assembly.
- Services Aerospace and Defense and Industrial
- ITAR controlled facility ISO 9001:2008



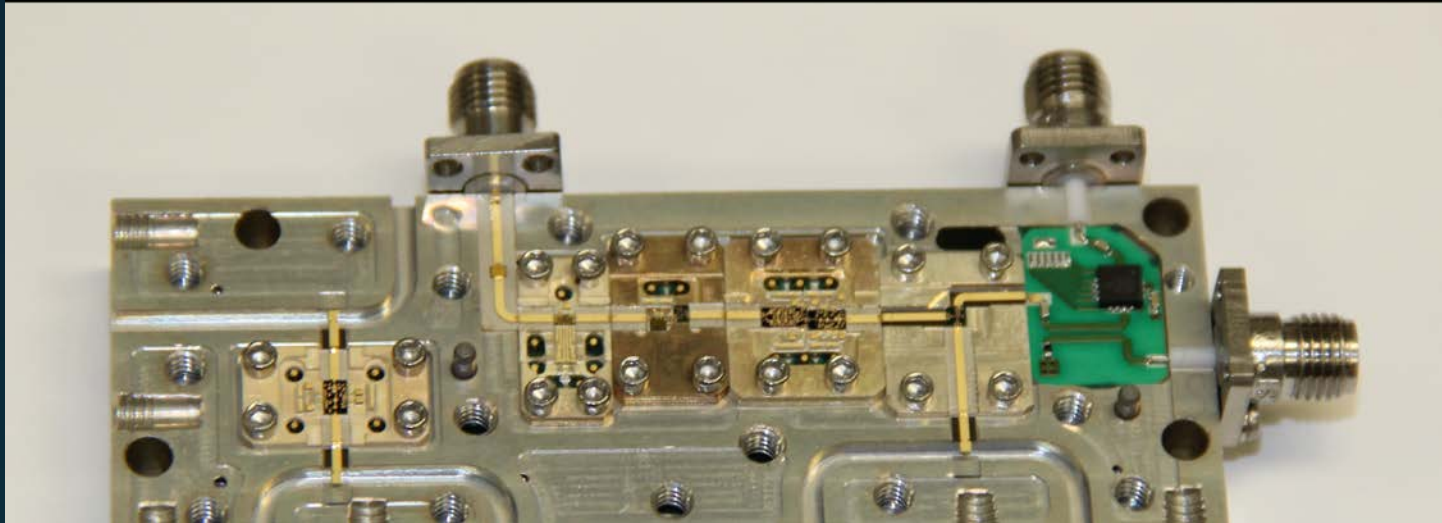
Overview

“Microwave and Millimeter Wave Multi-Chip Module Manufacturing”

- Multi-Chip module manufacturing for Microwave and Millimeter Wave Applications (30 GHz-100 GHz)
- Low to medium quantity build profile
- Design and manufacturing process geared to customization and optimized for a specific specification



Carrier-Based Millimeter Wave Transmitter



- Operating RF Frequency Range: 70 to 78 GHz
- Carrier-Based Subassemblies
- Quartz & Duroid 5880 transmission lines
- GaAs MMICs
- Glass/metal feedthrus to carry DC bias from opposite side
- FR4-Based IF circuit

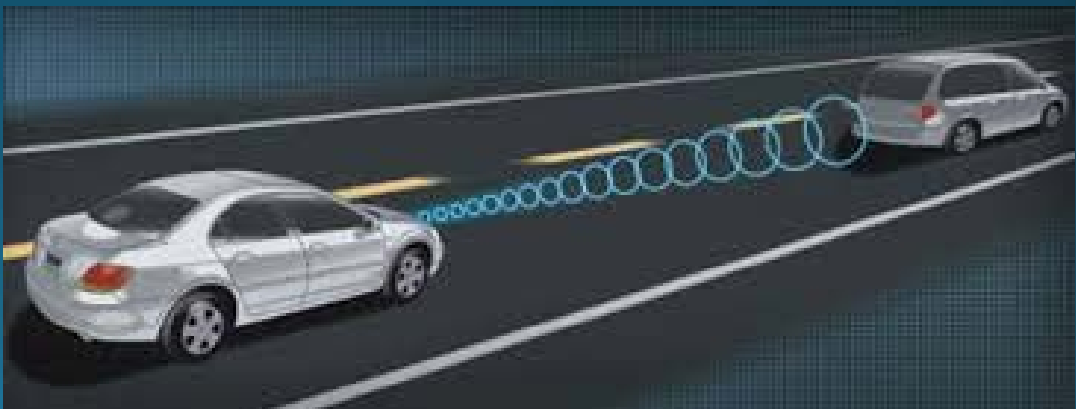
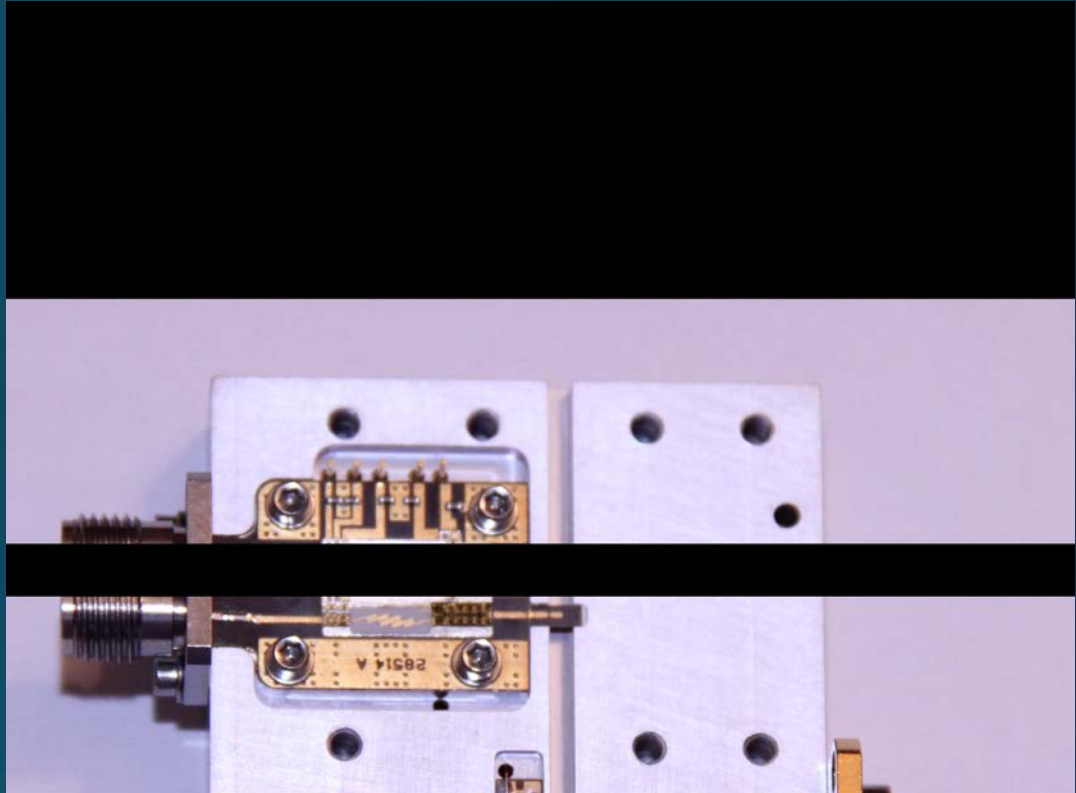
Carrier-Based Construction

- Replacable carrier subassemblies
- Quartz Waveguide Launch & Transmission Lines
- GaAs MMICs
- Glass/metal feedthrus to carry DC bias from opposite side



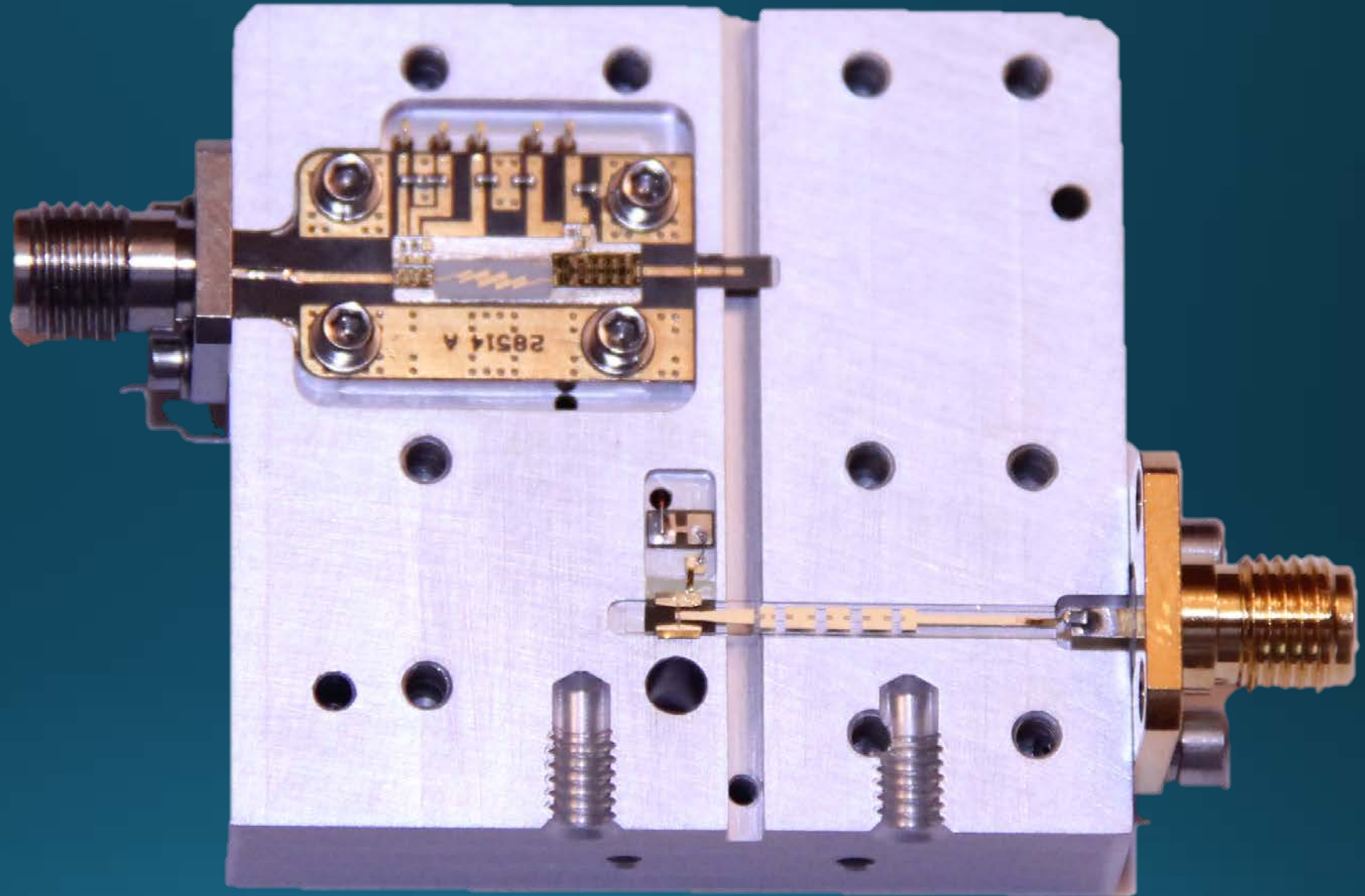
E-Band Integrated Mixer/LO Multiplier Modules

- Used in HXI 71-76/81-86 GHz radios
- Used in test equipment configurations for production testing of automotive radar MMIC transceivers and complete radar modules
- Carrier-based multiplier circuit using GaAs MMICs & alumina BPF
- High performance mixer using beam lead diodes and quartz substrate in a suspended stripline medium
- Glass/metal feedthrus to bring DC bias from backside regulator/sequencer



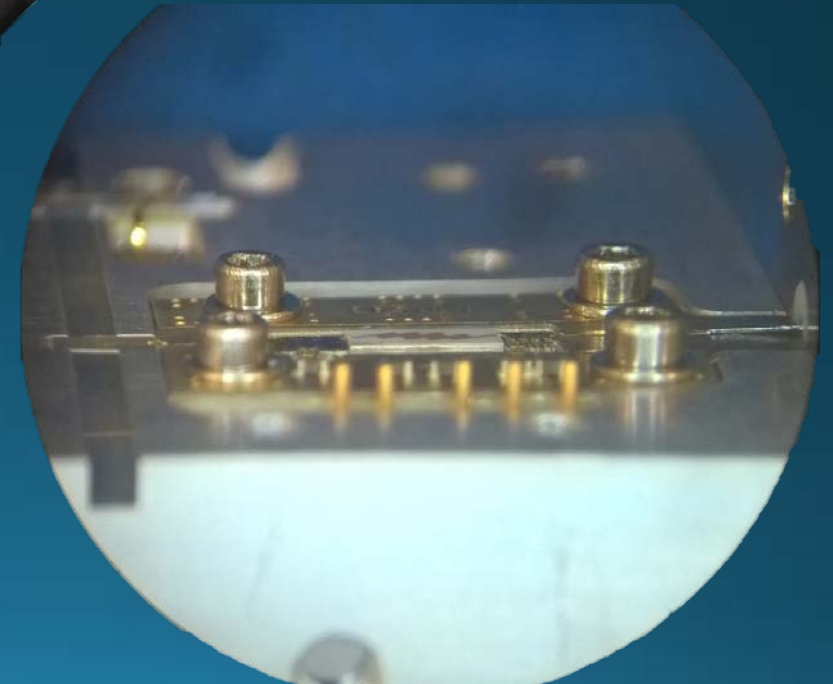
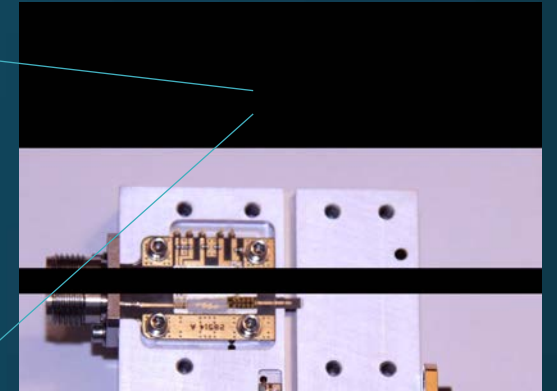
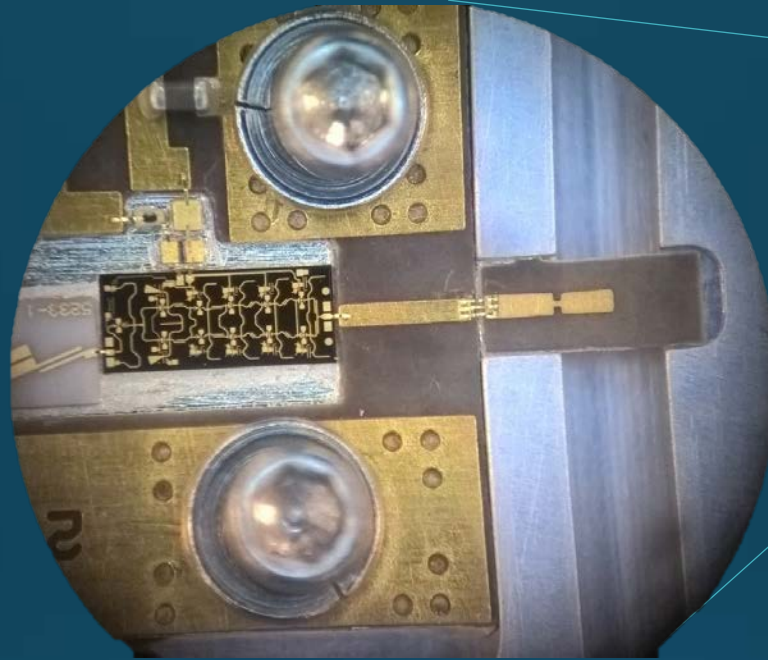
Mixed Media

- Combined Alumina, Quartz, 5880 Duroid, Carrier integration
- Discrete Beam Lead Diodes, MMIC, SMT components
- Micro-Strip, Suspended Stripline, Coaxial, Stripline
- Solder, epoxy paste, epoxy film



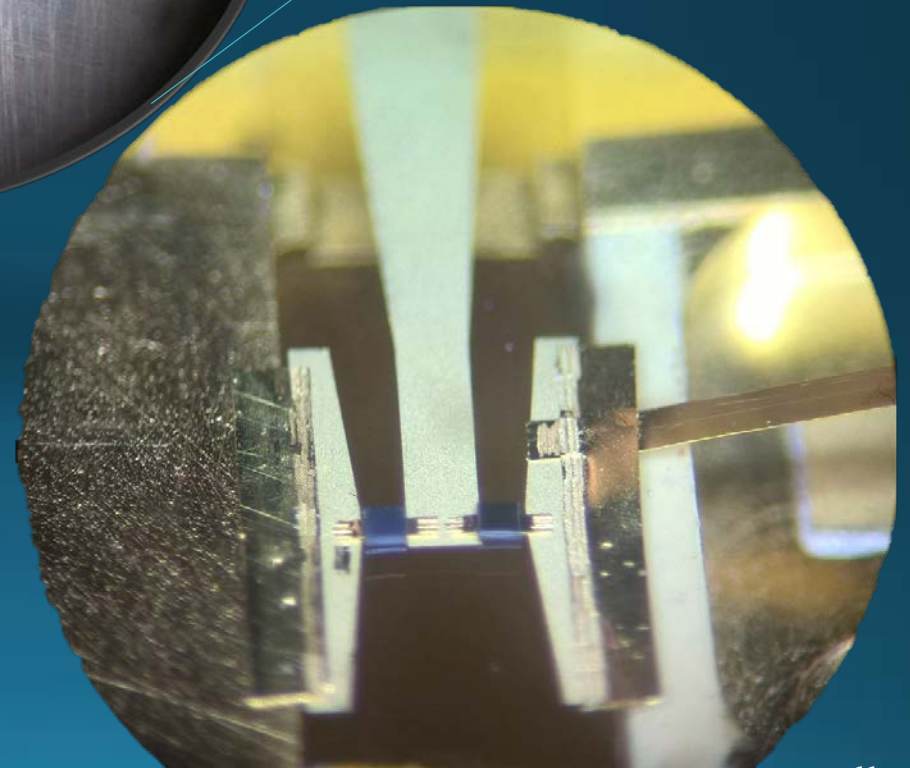
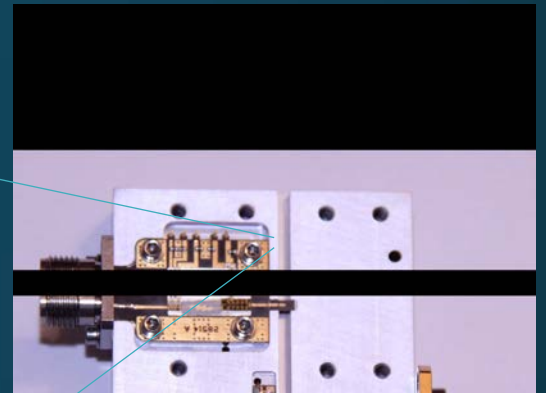
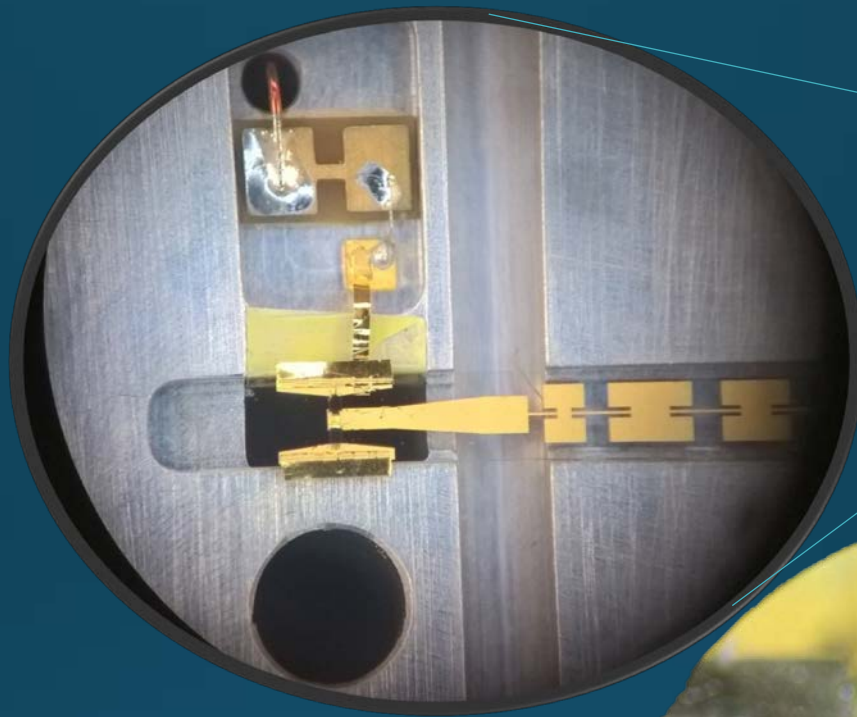
Bonding to Mixed Media

- Duroid, GaAs, Alumina
- Keeping Bond Looping low
- Z Axis control



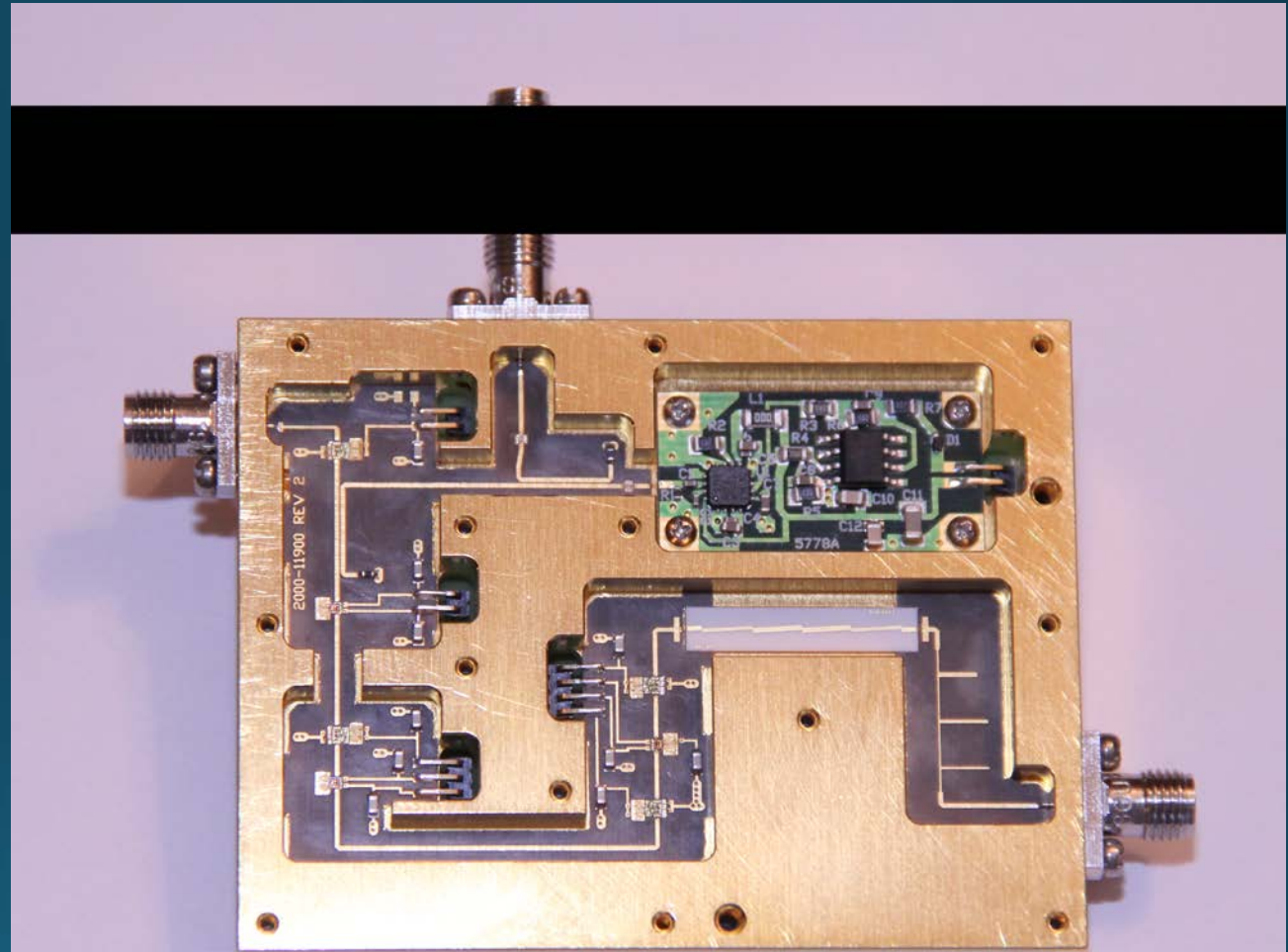
Bonding on Suspended Media

- Quartz suspended strip-line
- Discrete Beam Lead Diodes,
- Thermo-Compression bond on Au Ribbon and Beam Lead Diode



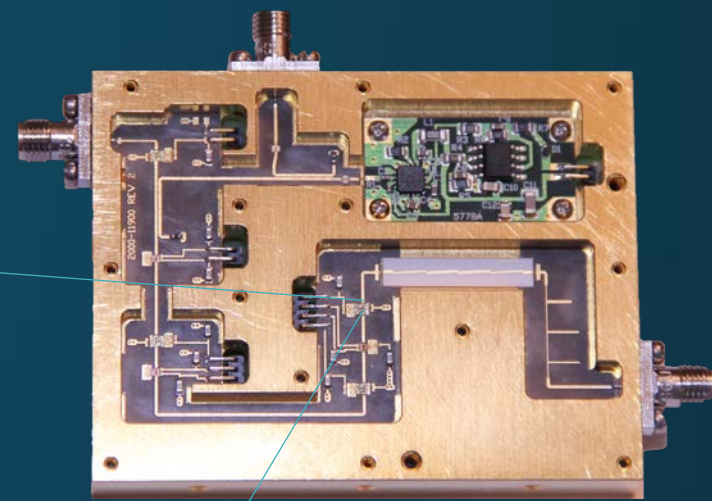
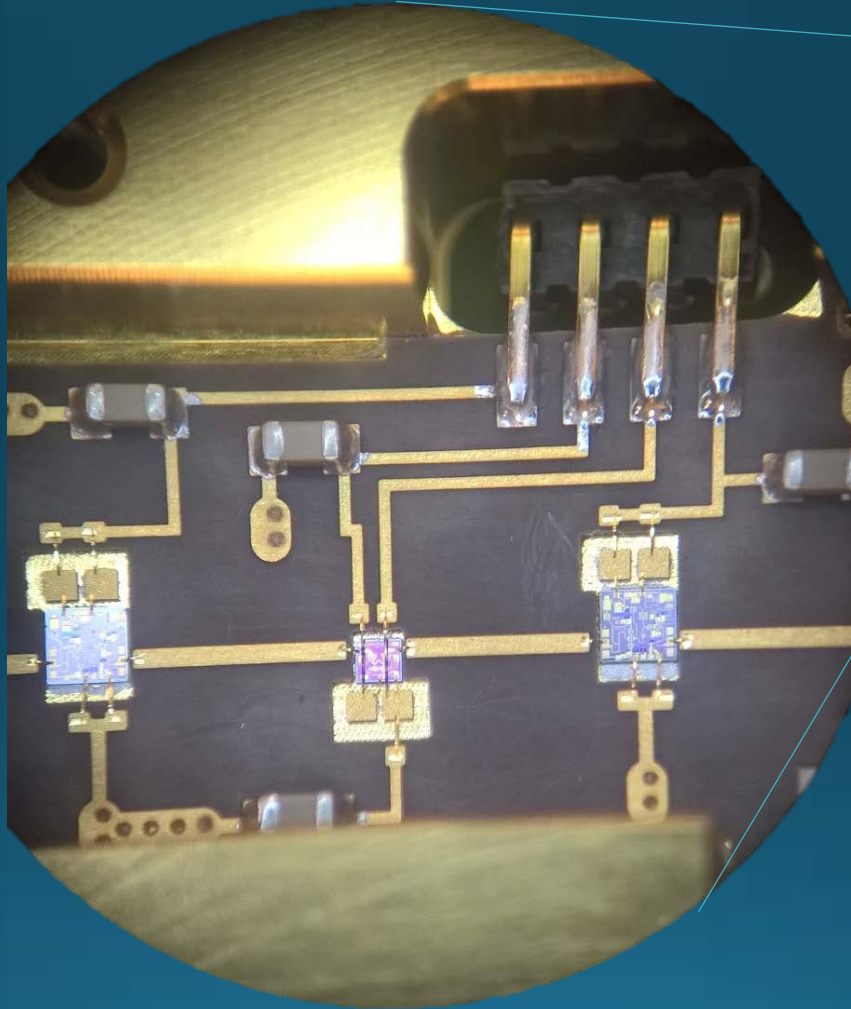
C-Band AGC Amplifier Module

- 4 to 9 GHz
- 70 dB Total Gain
- 50 dB Attenuation Range
- Duroid 5880 Base material
- GaAs MMICs (bare die)
- Alumina BPF



Mixed SMT with Hybrid Chip & Wire

- Soldered Bypass Capacitors
- Epoxy MMIC's single layer capacitors
- 2 mil Au ribbon bonds
- Soldered SIP bias lines



Thank you!!